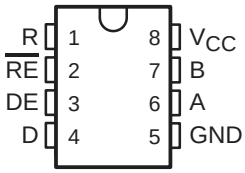
SLLS212B – SEPTEMBER 1995 – REVISED APRIL 1998

- **Bidirectional Transceiver With Fail-Safe Receiver**
- **Meets or Exceeds the Requirements of ITU Recommendation V.11**
- **Electrically Compatible With ANSI Standards TIA/EIA-422-B and TIA/EIA-485-A**
- **Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments**
- **3-State Driver and Receiver Outputs**
- **Individual Driver and Receiver Enables**
- **Wide Positive and Negative Input/Output Bus Voltage Ranges**
- **Driver Output Capability . . . ±60 mA Max**
- **Thermal Shutdown Protection**
- **Driver Positive and Negative Current Limiting**
- **Receiver Input Impedance . . . 12 kΩ Min**
- **Receiver Input Sensitivity . . . –300 mV/0 mV**
- **Operates From Single 5-V Supply**
- **Pin-to-Pin Compatible With SN75176A**

D OR P PACKAGE
(TOP VIEW)



description

The SN75276 differential bus transceiver is a monolithic, integrated circuit designed for bidirectional data communication on multipoint bus transmission lines. It is designed for balanced transmission lines and is electrically compatible with ANSI Standards TIA/EIA-422-B and TIA/EIA-485-A, and meets ITU Recommendation V.11.

The fail-safe operation ensures a known level on the circuit output under bus fault conditions. The circuit provides a high-level output under floating-line, idle-line, open-circuit, and short-circuit bus conditions (see Function Tables).

The SN75276 combines a 3-state, differential line driver and a differential input line receiver, both of which operate from a single, 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, that can be externally connected together to function as a direction control. The driver differential outputs and the receiver differential inputs are connected internally to form differential input/output (I/O) bus ports that are designed to offer minimum loading to the bus whenever the driver is disabled or V_{CC} = 0. These ports feature wide positive and negative common-mode voltage ranges making the device suitable for party-line applications.

The driver is designed for up to 60 mA of sink or source current. The driver features positive- and negative-current limiting and thermal shutdown for protection from line fault conditions. Thermal shutdown is designed to occur at a junction temperature of approximately 150°C. The receiver features a minimum input impedance of 12 kΩ.

The SN75276 can be used in transmission line applications employing the SN75172 and SN75174 quadruple differential line drivers and SN75173 and SN75175 quadruple differential line receivers.

SN75276 is characterized for operation from 0°C to 70°C.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Function Tables

EACH DRIVER

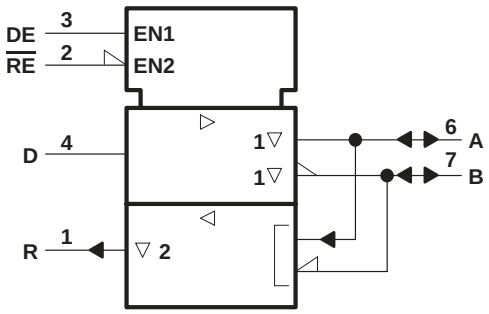
INPUT D	ENABLE DE	OUTPUTS A	OUTPUTS B
H	H	H	L
L	H	L	H
X	L	Z	Z

EACH RECEIVER

DIFFERENTIAL A – B	ENABLE $\overline{RE}$	OUTPUT R
$V_{ID} \geq 0$ V	L	H
-0.3 V < V_{ID} < 0 V	L	?
$V_{ID} \leq -0.3$	L	L
X	H	Z
Open	L	H

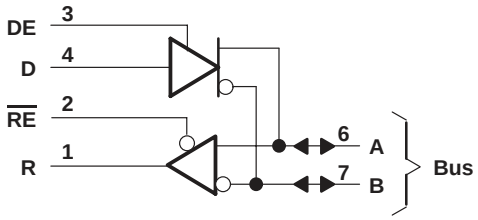
H = high level, L = low level, ? = indeterminate,
X = irrelevant, Z = high impedance (off)

logic symbol†

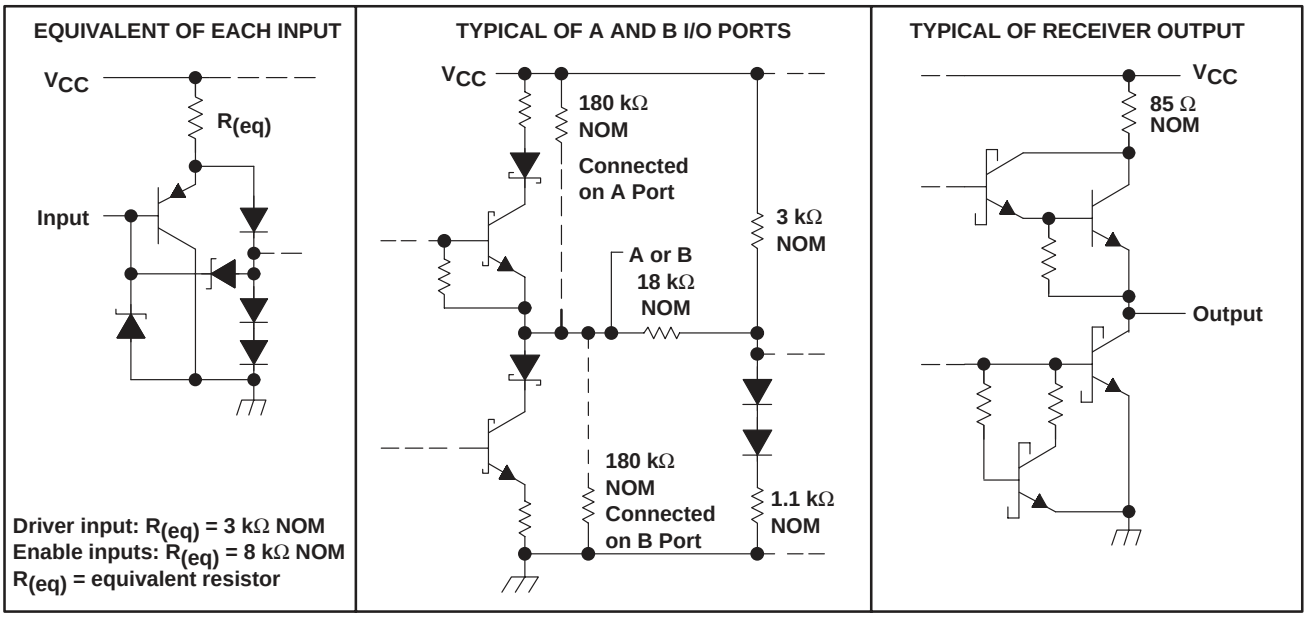


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Voltage at any bus terminal . . . . . –10 V to 15 V
Enable input voltage, V_I . . . . . 5.5 V
Continuous total power dissipation . . . . . See Dissipation Rating Table
Storage temperature range, T_{stg} . . . . . – 65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential input/output bus voltage, are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 105°C$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW	261 mW
P	1100 mW	8.8 mW/°C	704 mW	396 mW

recommended operating conditions

		MIN	TYP	MAX	UNIT
Supply voltage, V_{CC}		4.75	5	5.25	V
Voltage at any bus terminal (separately or common mode), V_I or V_{IC}				12	V
				−7	
High-level input voltage, V_{IH}	D, DE, and $\overline{RE}$	2			V
Low-level input voltage, V_{IL}	D, DE, and $\overline{RE}$			0.8	V
Differential input voltage, V_{ID} (see Note 2)				±12	V
High-level output current, I_{OH}	Driver			−60	mA
	Receiver			−400	μA
Low-level output current, I_{OL}	Driver			60	mA
	Receiver			8	
Operating free-air temperature, T_A		0		70	°C

NOTE 2: Differential input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.

DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
V_{IK}	Input clamp voltage	I_I = –18 mA				–1.5	V
V_O	Output voltage	I_O = 0		0		6	V
$\|V_{OD1}\|$	Differential output voltage	I_O = 0		1.5	3.6	6	V
$\|V_{OD2}\|$	Differential output voltage	R_L = 100 Ω, See Figure 1		1/2 V_{OD1} or 2§			V
		R_L = 54 Ω, See Figure 1		1.5	2.5	5	V
V_{OD3}	Differential output voltage	See Note 3		1.5		5	V
$\Delta\|V_{OD}\|$	Change in magnitude of differential output voltage¶	R_L = 54 Ω or 100 Ω, See Figure 1				±0.2	V
V_{OC}	Common-mode output voltage					+3 –1	V
$\Delta\|V_{OC}\|$	Change in magnitude of common-mode output voltage¶					±0.2	V
I_O	Output current	Output disabled, See Note 4	V_O = 12 V			1	mA
			V_O = – 7 V			–0.8	
I_{IH}	High-level input current	V_I = 2.4 V				20	µA
I_{IL}	Low-level input current	V_I = 0.4 V				–400	µA
I_{OS}	Short-circuit output current	V_O = –7 V				–250	mA
		V_O = 0				150	
		V_O = V_{CC}				250	
		V_O = 12 V				250	
I_{CC}	Supply current (total package)	No load	Outputs enabled		42	70	mA
			Outputs disabled		26	35	

† The power-off measurement in ANSI Standard TIA/EIA-422-B applies to disabled outputs only and is not applied to combined inputs and outputs.
‡ All typical values are at V_{CC} = 5 V and T_A = 25°C.
§ The minimum V_{OD2} with a 100-Ω load is either 1/2 V_{OD1} or 2 V, whichever is greater.
¶ $\Delta|V_{OD}|$ and $\Delta|V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.

NOTES: 3. This applies for both power on and off; refer to TIA/EIA-485-A for exact conditions. The TIA/EIA-422-B limit does not apply for a combined driver and receiver terminal.
4. See TIA/EIA-485-A Figure 3.5, Test Termination Measurement 2.

switching characteristics, V_{CC} = 5 V, R_L = 110 kΩ, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$t_{d(OD)}$	Differential-output delay time	R_L = 54 Ω,	See Figure 3		15	22	ns
$t_{t(OD)}$	Differential-output transition time				20	30	ns
t_{PZH}	Output enable time to high level	See Figure 4			85	120	ns
t_{PZL}	Output enable time to low level	See Figure 5			40	60	ns
t_{PHZ}	Output disable time from high level	See Figure 4			150	250	ns
t_{PLZ}	Output disable time from low level	See Figure 5			20	30	ns

DRIVER SECTION

SYMBOL EQUIVALENTS

DATA-SHEET PARAMETER	TIA/EIA-422-B	TIA/EIA-485-A
V_O	V_{oa}, V_{ob}	V_{oa}, V_{ob}
$\|V_{OD1}\|$	V_o	V_o
$\|V_{OD2}\|$	V_t (R_L = 100 Ω)	V_t (R_L = 54 Ω)
V_{OD3}	None	V_t (Test Termination Measurement 2)
$\Delta\|V_{OD}\|$	$\|\|V_t\| - \|\overline{V}_t\|\|$	$\|\|V_t - \|\overline{V}_t\|\|$
V_{OC}	$\|V_{os}\|$	$\|V_{os}\|$
$\Delta\|V_{OC}\|$	$\|V_{os} - \overline{V}_{os}\|$	$\|V_{os} - \overline{V}_{os}\|$
I_{OS}	$\|I_{sa}\|$, $\|I_{sb}\|$	
I_O	$\|I_{xa}\|$, $\|I_{xb}\|$	I_{ia}, I_{ib}

RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage	V_O = 2.7 V,	I_O = –0.4 mA			0	V
V_{IT-}	Negative-going input threshold voltage	V_O = 0.5 V,	I_O = 8 mA	–0.3‡			V
V_{IK}	Enable clamp voltage	I_I = –18 mA				–1.5	V
V_{OH}	High-level output voltage	V_{ID} = 0, See Figure 2	I_{OH} = –400 μA,	2.7			V
V_{OL}	Low-level output voltage	V_{ID} = –300 mV, See Figure 2	I_{OL} = 8 mA,			0.45	V
I_{OZ}	High-impedance-state output current	V_O = 0.4 V to 2.4 V				±20	μA
I_I	Line input current	Other input = 0 V, See Note 5	V_I = 12 V			1	mA
			V_I = –7 V			–0.8	
I_{IH}	High-level enable input current	V_{IH} = 2.7 V				20	μA
I_{IL}	Low-level enable input current	V_{IL} = 0.4 V				–100	μA
r_i	Input resistance	V_I = 12 V		12			kΩ
I_{OS}	Short-circuit output current			–15		–85	mA
I_{CC}	Supply current (total package)	No load	Outputs enabled		42	55	mA
			Outputs disabled		26	35	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet for negative-going input threshold voltage levels only.
NOTE 5: This applies for both power on and power off. Refer to TIA/EIA-485-A for exact conditions.

RECEIVER SECTION

switching characteristics, V_{CC} = 5 V, C_L = 15 pF, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	V_{ID} = 0 to 3 V, See Figure 6		21	35	ns
t_{PHL}	Propagation delay time, high- to low-level output			23	35	ns
t_{PZH}	Output enable time to high level	See Figure 7		10	20	ns
t_{PZL}	Output enable time to low level			12	20	ns
t_{PHZ}	Output disable time from high level	See Figure 7		20	35	ns
t_{PLZ}	Output disable time from low level			17	25	ns

PARAMETER MEASUREMENT INFORMATION

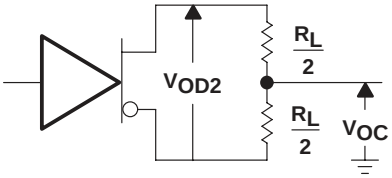


Figure 1. Driver V_{OD} and V_{OC}

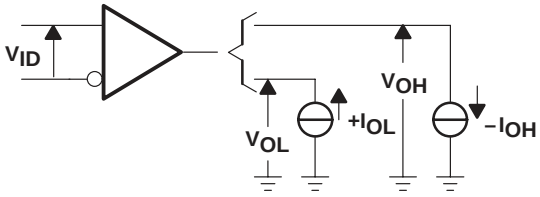
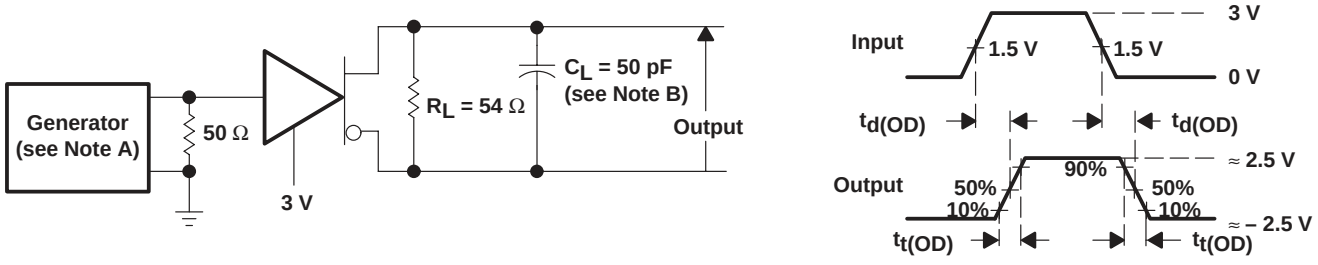


Figure 2. Receiver V_{OH} and V_{OL}

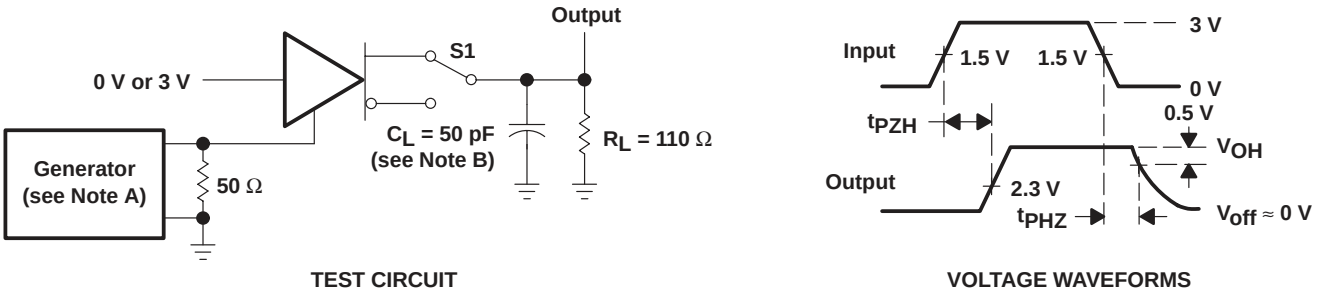


TEST CIRCUIT **VOLTAGE WAVEFORMS**

NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

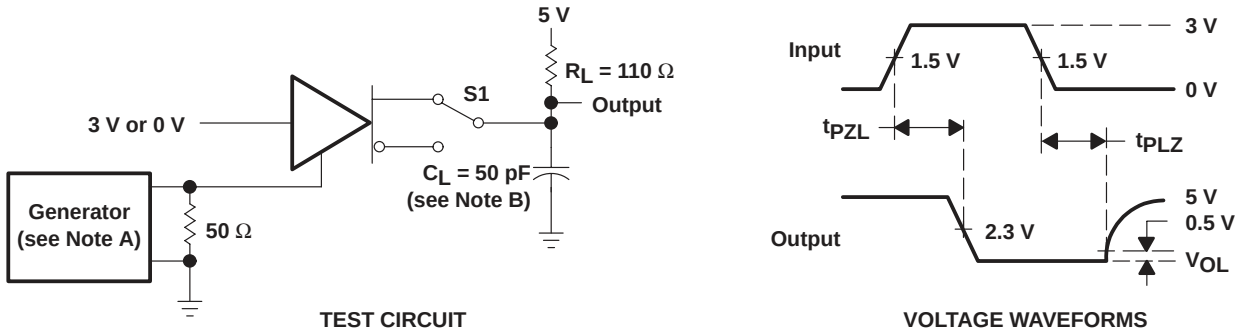
Figure 3. Driver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



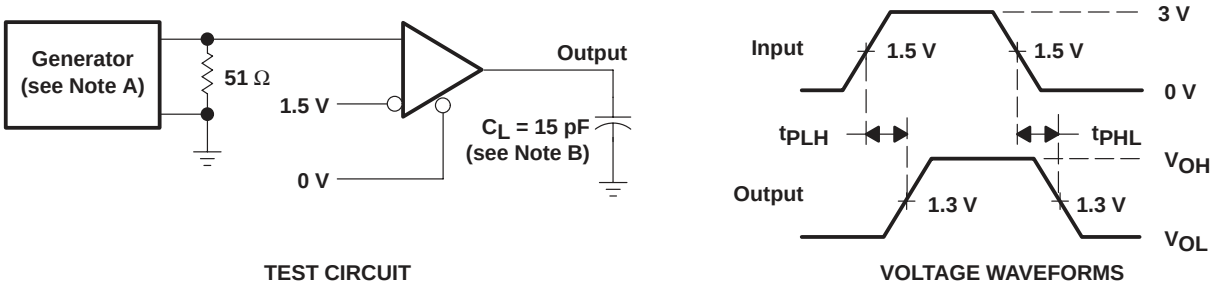
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

Figure 4. Driver Test Circuit and Voltage Waveforms



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

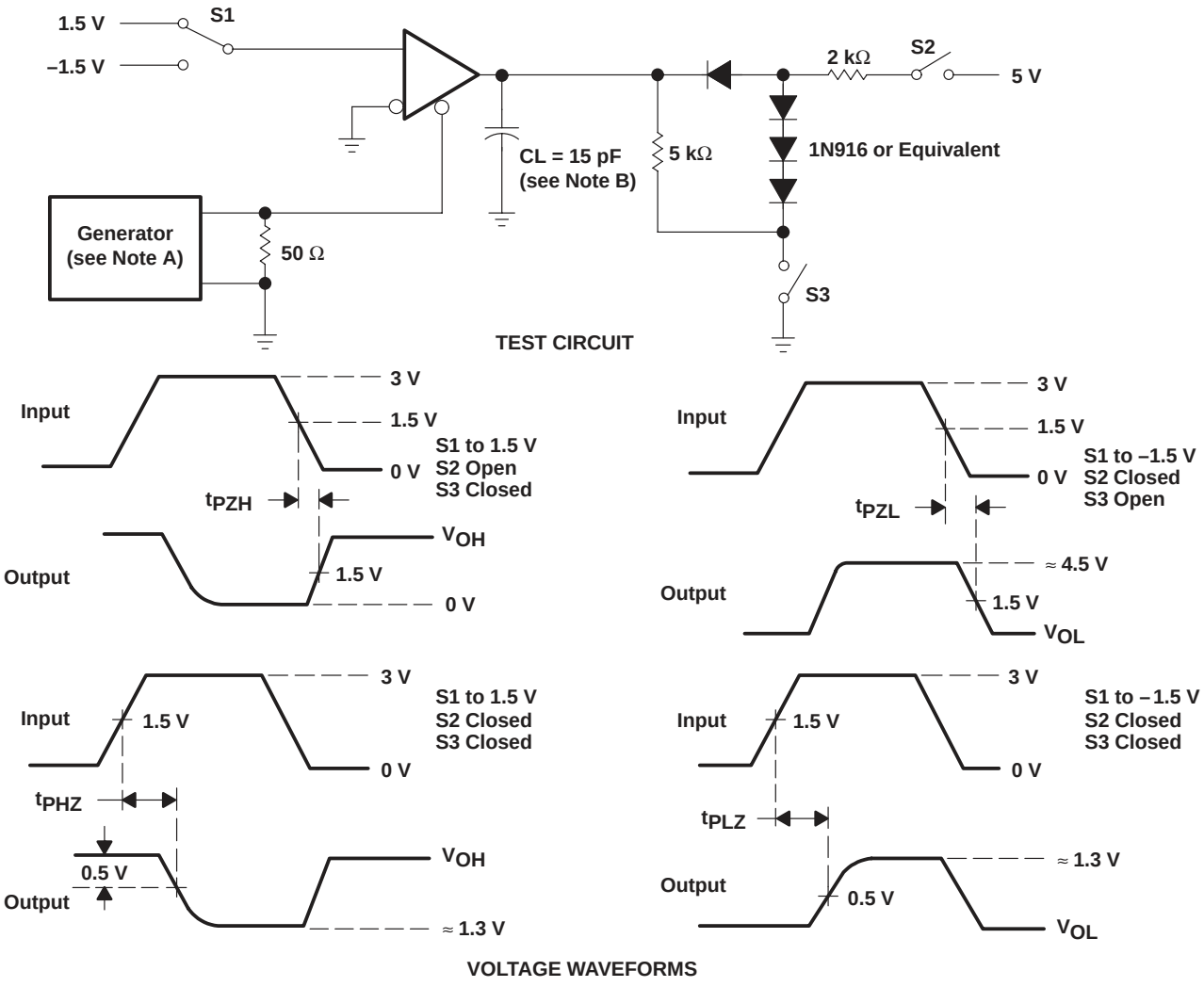
Figure 5. Driver Test Circuit and Voltage Waveforms



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

Figure 6. Receiver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS

NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

Figure 7. Receiver Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

DRIVER
HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

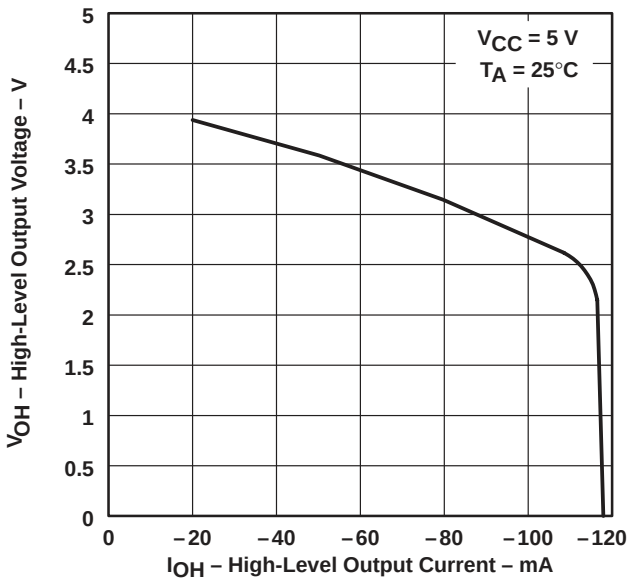


Figure 8

DRIVER
LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

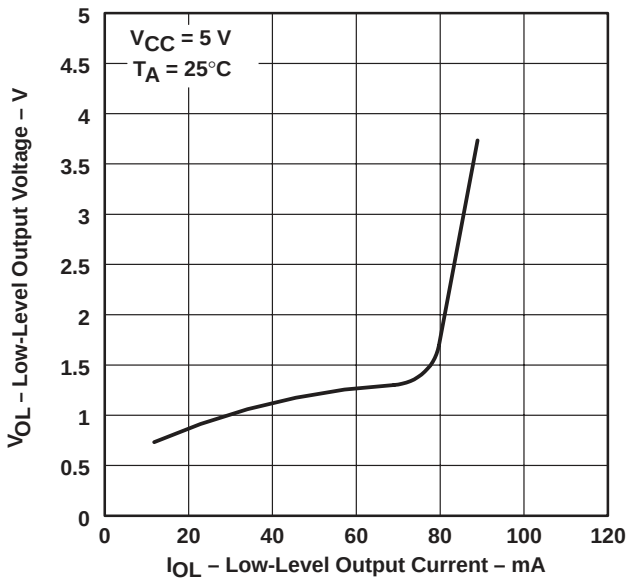


Figure 9

DRIVER
DIFFERENTIAL OUTPUT VOLTAGE
vs
OUTPUT CURRENT

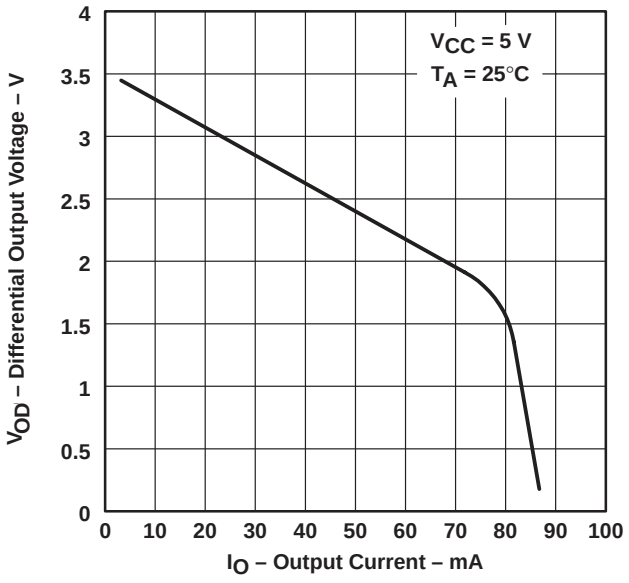


Figure 10

TYPICAL CHARACTERISTICS†

RECEIVER
HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

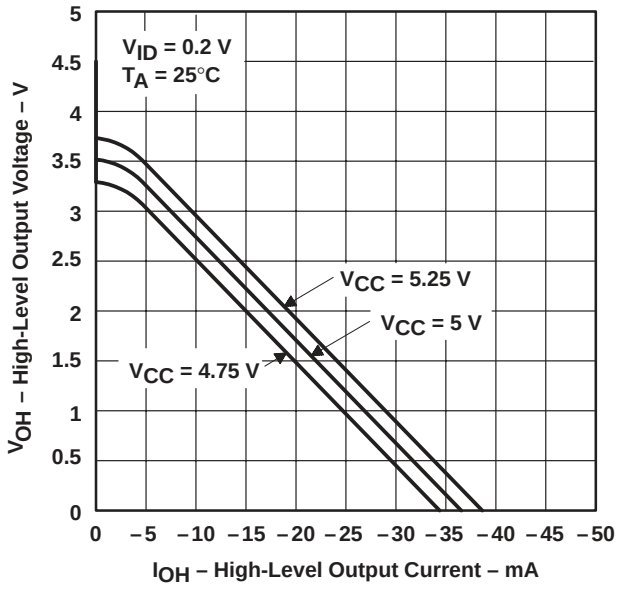


Figure 11

RECEIVER
HIGH-LEVEL OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE

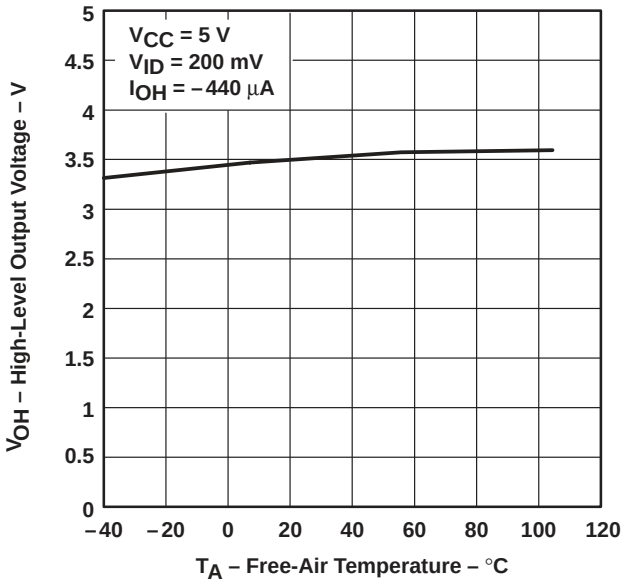


Figure 12

RECEIVER
LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

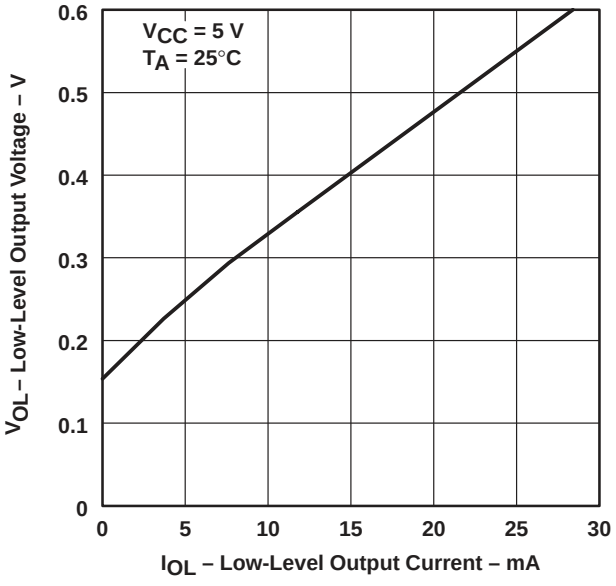


Figure 13

RECEIVER
LOW-LEVEL OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE

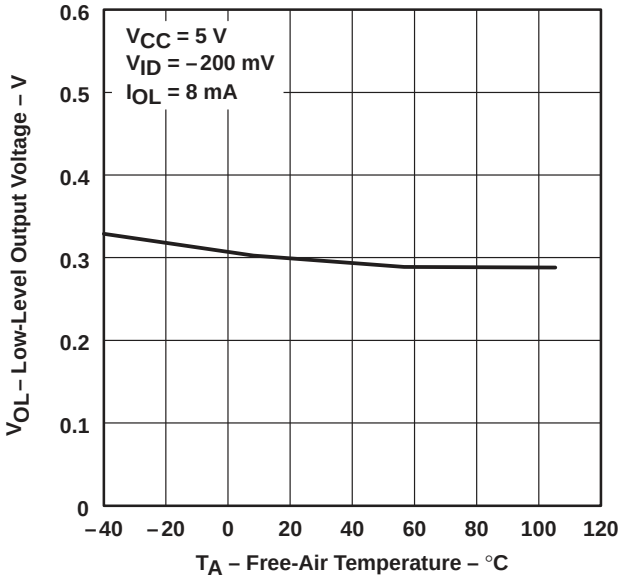


Figure 14

† Operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied.

TYPICAL CHARACTERISTICS

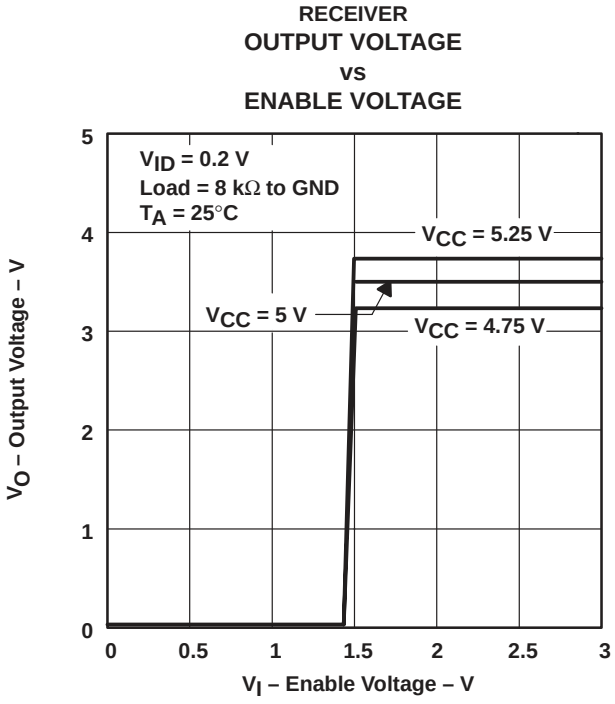


Figure 15

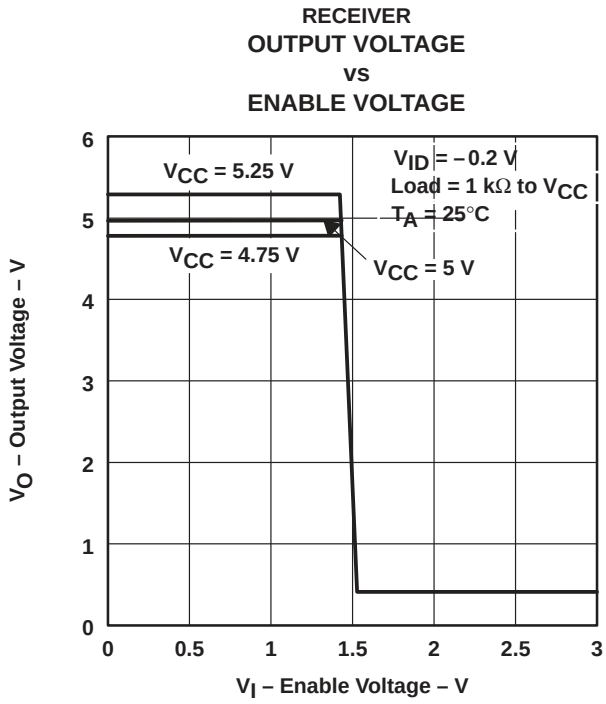
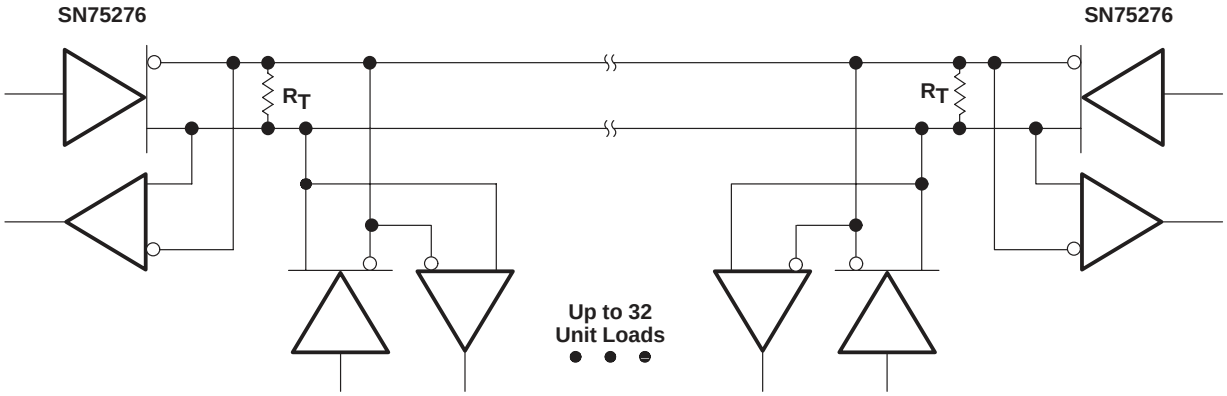


Figure 16

APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance. Stub lengths off the main line should be kept as short as possible ($R_T = Z_O$).

Figure 17. Typical Application Circuit

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN75276D	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	0 to 70		
SN75276DR	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	0 to 70		
SN75276P	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI	0 to 70		

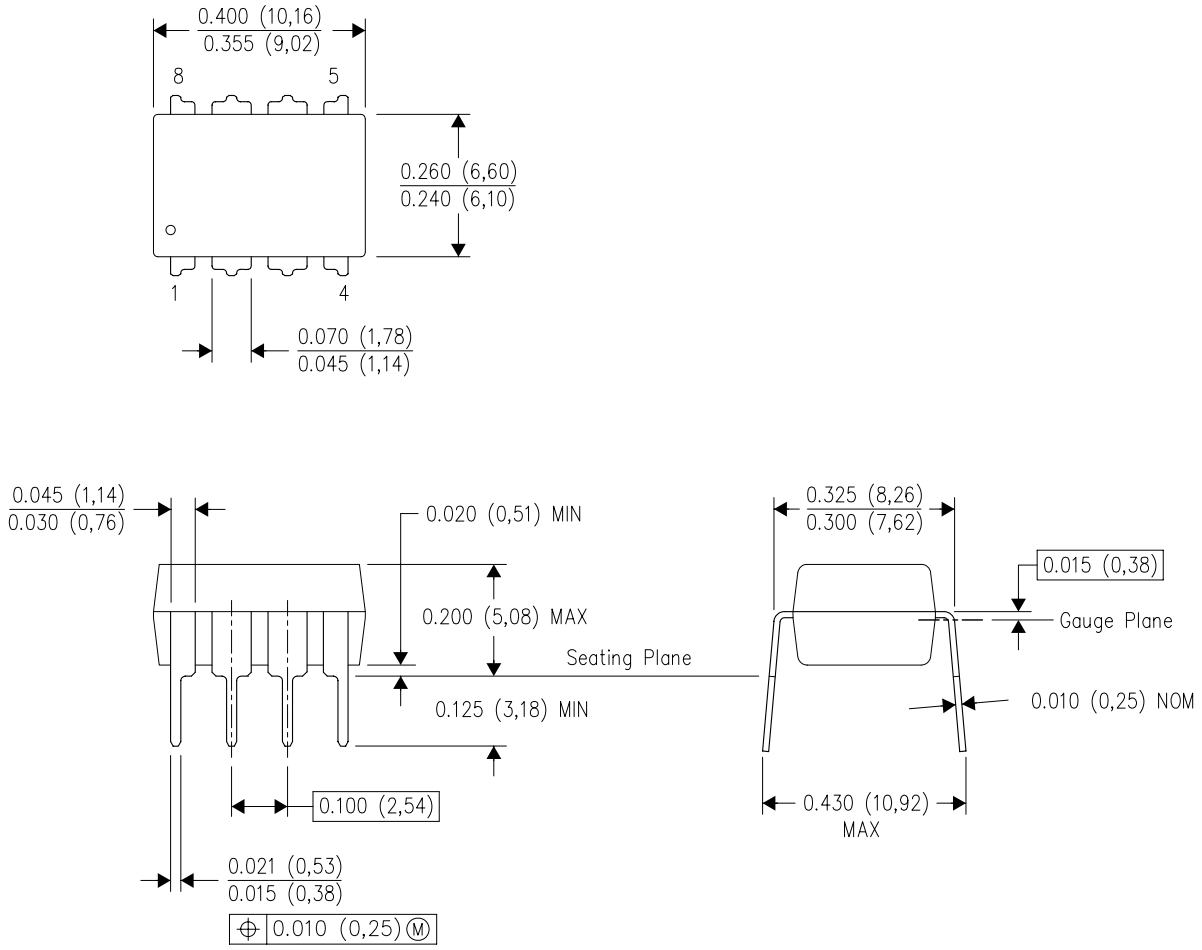
(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

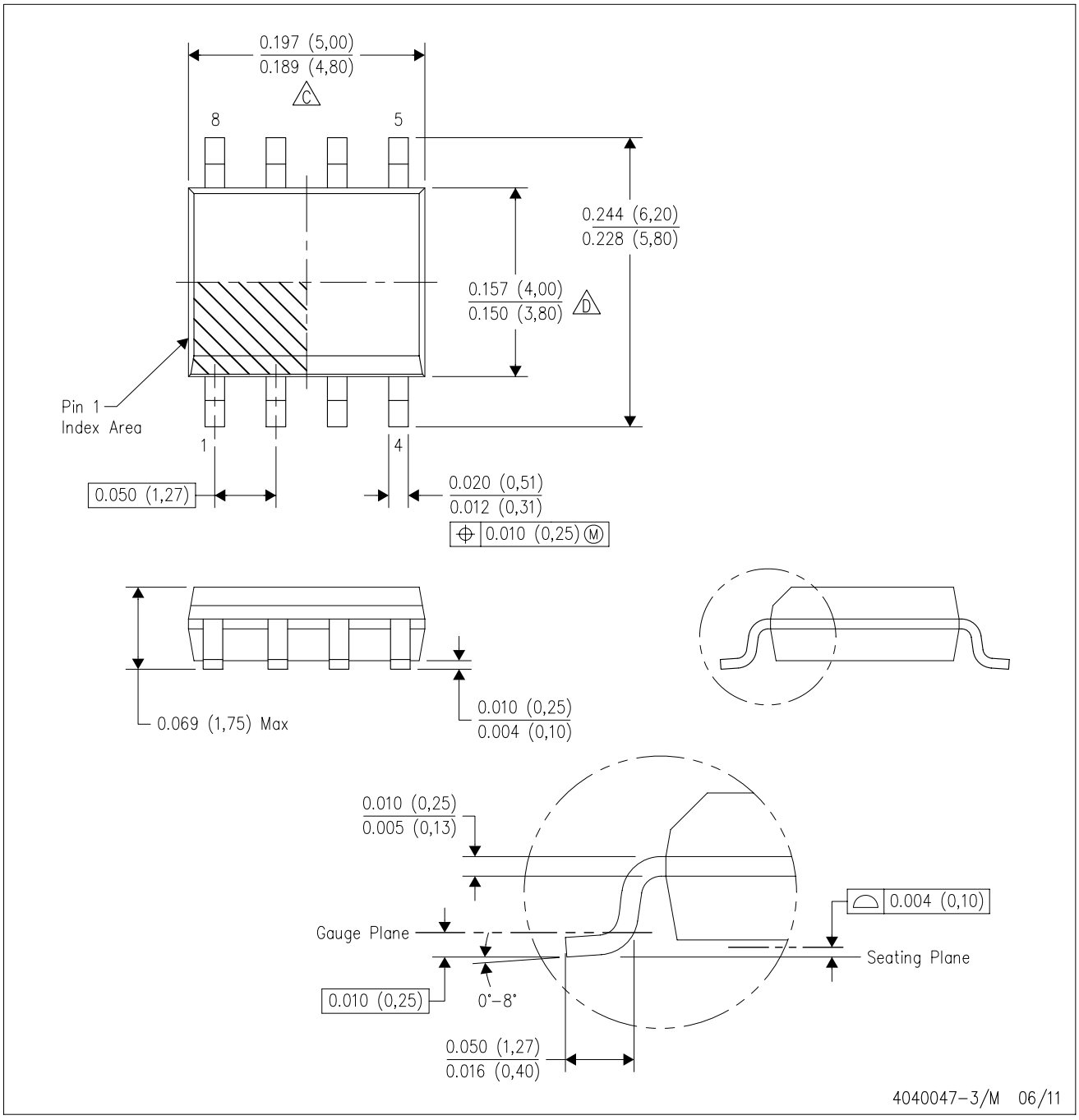
(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AA.

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